

# MA2Z030 Series (MA30 Series)

## Silicon epitaxial planar type

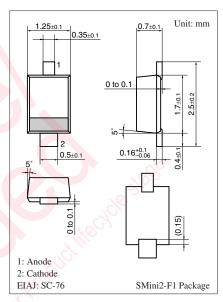
For reduced voltage and temperature compensation

#### ■ Features

- S-mini type package, allowing high-density mounting
- Extremely small reverse current I<sub>R</sub>
- Large power dissipation P<sub>D</sub>
- Wide forward voltage V<sub>F</sub> range

#### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter		Symbol	Rating	Unit	
Reverse voltage		$V_R$	6	V	
Peak forward	MA2Z030A/B	$I_{FM}$	150	mA	
current	MA2Z030WA/WB		100		
Power dissipation		$P_{\mathrm{D}}$	100	mW	
Junction temperature		$T_{j}$	125	°C	
Storage temperature		$T_{stg}$	-55 to +125	°C	



#### Marking Symbol

MA2Z0300A: 3A
MA2Z0300B: 3B
MA2Z030WA: 3C
MA2Z030WB: 3D

### ■ Electrical Characteristics $T_a = 25$ °C ± 3°C \*1

Parameter		Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	MA2Z030A	$V_{F1}$	I <sub>F</sub> = 1.5 mA	0.56	, .C	0.61	V
	MA2Z030B	16	of the siller co. The	0.59		0.64	
	MA2Z030WA/WB	illo	$I_F = 10 \mu A$	0.77	5		
Forward voltage	MA2Z030WA	$V_{F2}$	$I_F = 3 \text{ mA}$	1.18		1.28	V
	MA2Z030WB			1.26		1.36	
Reverse current		$I_R$	$V_R = 6 \text{ V}$			1.0	μΑ
Temperature coefficient	MA2Z030A/B	$-\Delta V_F / \Delta T$	I <sub>F</sub> = 1.5 mA		2.0		mV/°C
of forward voltage *2	MA2Z030WA/WB		$I_F = 3 \text{ mA}$		4.6		

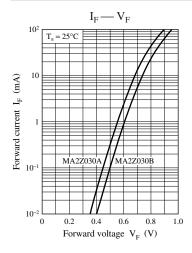
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

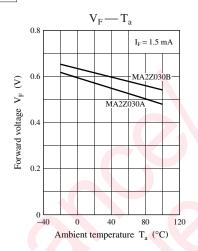
- 2. Absolute frequency of input and output is 100 MHz.
- 3. \*1: The temperature must be controlled 25°C for  $V_F$  measurement.  $V_F$  value measured at other temprature must be adjusted to  $V_F$  (25°C).

\*2:  $T_i = 25^{\circ}C$  to  $125^{\circ}C$ 

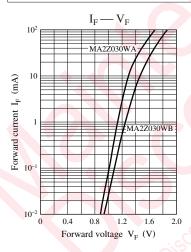
Note) The part numbers in the parenthesis show conventional part number.

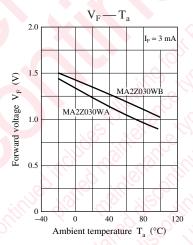
#### Characteristics charts of MA2Z030





#### Characteristics charts of MA2Z030W





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